

## C1206X332M3GEC

ESD SMD Comm COG, Ceramic, 3,300 pF, 20%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206, 1.5 mm



Click [here](#) for the 3D model.

### General Information

Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

### Dimensions

Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
T	0.78mm +/-0.20mm
S	1.5mm MIN
B	0.6mm +/-0.25mm

### Packaging Specifications

Packaging	Bulk, Bag
Packaging Quantity	1

### Specifications

Capacitance	3,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	25 VDC
ESD Level per AEC-Q200	16,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOHms

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